Product Specification

Product:	Palladium Paste For Filling Holes
Part Number:	60H-5901

Application Scope :

Applicable to high-temperature thick-film circuits, LTCC ceramics, and as conductive electrodes for via filling in laminated components.

Usage Conditions :

Substrate	Alumina ceramic, LTCC ceramic, laminated element
Printing	200-300 mesh screen printing
Drying &Sintering	① Single-layer printing (alumina plate) Furnace drying at 100-150°C for 10-15 minutes Air-fired sintering, peak temperature 850°C (minimum recommended value), 2-10 hours. The sintering temperature can be adjusted to 850–1400°C as needed.
	② Multilayer printing Remove the adhesive at a temperature range of 200-500°C for a minimum of 60 minutes. Air-fired sintering, peak temperature 850°C (minimum recommended value), 2-10 hours. The sintering temperature can be adjusted to 850–1400°C as needed.
Thinner	ST-1000

Characteristics :

1. Paste Characteristics :

Characteristic		Standard	Test Method And Conditions
1	Fineness	≤5μm	FOG test
2	Viscosity	280-530Pa.s	Brookfield HBT (Boli Fei) viscometer, rotor SC4-14/6R, operating at 10 rpm, with viscosity adjustable to 25±1°C according to user requirements.

2. Characteristics After Curing :

Under the 1-sintering condition, the film thickness is 8-12 μm.
Check fired film produced under the conditions specified in 1）, (Film thickness is 8-12μm.)

Characteristics		Standard	Test Method And Conditions
3	Resistivity	≤80mΩ/□	Test pattern 0.6mm×60mm
4	Adhesion Strength		Peel Test: 0.5mmφ Tin plated Cu wire soldered on 2mm×2mm Pad. Solder: 96.5Sn/0.5Cu Mildly activated flux used.
	Initial Adhesion	≥33.2N	

Save Conditions And Validity Period :

The product shall be stored in a sealed container at an ambient temperature of 5-25°C, with a shelf life of 1 year from the date of shipment.

Packaging Method :

Standard packaging, 1000g/can; samples are available in 200g small can packaging.